52-LEAD 8mm P=0.50mm
QFN CAVITY PACKAGE

Notes: (Unless Otherwise Specified)
1) BODY: PLASTIC, SEMICONDUCTOR GRADE
2) LEAD FRAME: COPPER, C-194F/H
3) LEAD FRAME PLATING: Ni, Pd, Au
4) FRAME THICKNESS: 0.203mm
5) DIE PAD: 6.39 X 6.39mm
6) JEDEC OUTLINE: MO-220

www.MirrorSemi.com
TOP VIEW

SIDE VIEW
(BEFORE LID ATTACH)

BOTTOM VIEW

CAVITY WALL

52 51 50 49 48 47 46 45 44 43 42 41 40

1 2 3 4 5 6 7 8 9 10 11 12 13

14 15 16 17 18 19 20 21 22 23 24 25 26

14 15 16 17 18 19 20 21 22 23 24 25 26

0.840

45° CHAMFER

8

0.500

52 51 50 49 48 47 46 45 44 43 42 41 40

1 2 3 4 5 6 7 8 9 10 11 12 13

14 15 16 17 18 19 20 21 22 23 24 25 26

Title:
52-LEAD 8mm P=0.50mm
QFN CAVITY PACKAGE

Lead Numbering

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Mirror
Semiconductor™

Title:
52-LEAD 8mm P=0.50mm
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Lead Numbering

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Scale:
8:1

Size:
A

Drawing No.:
455270

Rev.:
A

Do not Scale Drawing

Sheet 2 of 4
Notes: (Unless Otherwise Specified).
1. DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE BASE WHEN DESIGNING THE PCB.
2. SURROUND EACH SIDE OF I/O PERIMETER PADS WITH 0.060~0.075 mm (2.4~3.0mils) NSMD SOLDER MASK OPENING. OPTIONALLY OK TO USE RECTANGLE (NSMD) MASK OPENING AROUND I/O PADS.
3. ROUNDED PCB LAND PADS REDUCE SOLDER BRIDGING. PAD CHAMFER ANGLE MAY VARY.
4. PCB LANDS SHOULD BE 0.2mm LONGER THAN THE PACKAGE I/O PADS.
5. THE WIDTH OF PERIMETER PCB PADS SHOULD MATCH (1:1) THE WIDTH OF THE PACKAGE PADS.
6. REFER TO INDUSTRY REFERENCES SUCH AS IPC-SM-782 FOR PCB LAND PATTERN DESIGN.
7. THERMAL GROUND PADS MAY BE CHANGED TO SUIT REQUIREMENTS OF THE DESIGNER.
   A. MAKE COPPER THERMAL PAD AS LARGE AS POSSIBLE.
   B. DRILL MULTIPLE THERMAL VIAS 0.25~0.33mm DIAMETER USING 0.8~1.2mm PITCH GRID.
   C. PLATE THERMAL VIA BARRELS WITH 1-OUNCE COPPER (18µm).
   D. TENT (COVER) THERMAL VIAS WITH SOLDER MASK 0.1mm LARGER THAN THE VIA DIAMETER.
8. STENCIL DESIGN MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
   A. LASER CUT STENCIL 0.125mm (5mil) THICK. APERTURE SIZE-TO-LAND RATIO OF 1:1.
   B. THE SOLDER PASTE OPENING IN THE THERMAL PAD AREA SHOULD BE A MATRIX ARRAY OF SMALLER APERATURES INSTEAD OF ONE LARGE APERATURE TO CONTROL PASTE AMOUNTS.
   C. APPLY 50% TO 80% SOLDER PASTE COVERAGE IN THE PAD AREA.